3 V, SUPER MINIMOLD MEDIUM POWER SI MMIC AMPLIFIER

UPC2762TB

VCC = 3.0 V

FEATURES

HIGH P1dB: 7 dBm TYP at 1.9 GHz
LOW VOLTAGE: 3.0 V TYP, 2.7 V MIN
WIDE BANDWIDTH: 2.9 GHz at -3 dB

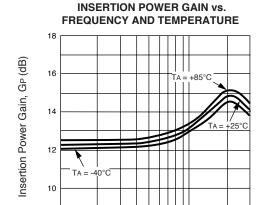
· SUPER SMALL PACKAGE: SOT-363 package

TAPE AND REEL PACKAGING OPTION AVAILABLE

DESCRIPTION

NEC's UPC2762TB is a Silicon Monolithic integrated circuit which is manufactured using the NESAT™ III process. The NESAT™ III process produces transistors with fT approaching 20 GHz. The UPC2762TB is pin compatible and has comparable performance to the larger UPC2762T, so it is suitable for use as a replacement to help reduce system size. The IC is housed in a 6 pin super minimold or SOT-363 package. Operating on a 3 volt supply, this IC is ideally suited for handheld, portable designs.

NEC's stringent quality assurance and test procedures ensure the highest reliability and performance.



Frequency, f (MHz)

ELECTRICAL CHARACTERISTICS (TA = 25°C, ZL = Zs = 50Ω, Vcc = 3.0 V)

	PAF PACK			UPC2762TB S06		
SYMBOLS	MBOLS PARAMETERS AND CONDITIONS		UNITS	MIN	TYP	MAX
Icc	Circuit Current (no signal)		mA		27	35
Gs	Small Signal Gain, f = f =	dB dB	11 11.5	13 15.5	16 17.5	
fu	Upper Limit Operating Fre (The gain at fu is 3 dB dov	GHz	2.7	2.9		
P _{1dB}	Output Power at 1 dB Con	dBm dBm	+5.5 +4.5	+8 +7		
Psat	Saturated Output Power,	f = 900 MHz f = 1900 MHz	dBm dBm		9 8.5	
NF	Noise Figure,	f = 900 MHz f = 1900 MHz	dB dB		6.5 7	8.0 9.0
RLIN	Input Return Loss,	dB dB	6 5.5	9 8.5		
RLout	Output Return Loss,	f = 900 MHz f = 1900 MHz	dB dB	8 9	11 12	
ISOL	Isolation,	f = 900 MHz f = 1900 MHz	dB dB	22 20	27 25	
OIP3	SSB Output Third Order Interd	tept Point f = 900, 902 MHz f = 1900, 1902 MHz	dBm dBm		+12 +9	
Padj	Adjacent Channel Power, f = 900 MHz, π/4 QPSK wa Po = +4 dBm		dBc dBc		-64 -64	

Note:

1. $\pi/4$ QPSK modulated wave input, data rate 42 kbps.

_California Eastern Laboratories

ABSOLUTE MAXIMUM RATINGS¹ (TA = 25°C)

SYMBOLS	PARAMETERS	UNITS	RATINGS
Vcc	Supply Voltage	V	3.6
Icc Total Supply Current		mA	70
PIN Input Power		dBm	+10
Рт	Total Power Dissipation ²	mW	200
Тор	Operating Temperature	°C	-40 to +85
Tstg	Storage Temperature	°C	-55 to +150

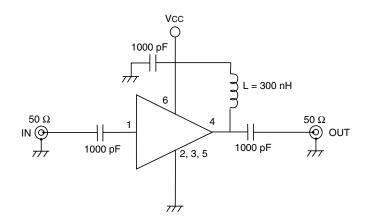
Notes:

- Operation in excess of any one of these parameters may result in permanent damage.
- 2. Mounted on a 50 x 50 x 1.6 mm epoxy glass PWB ($T_A = 85$ °C).

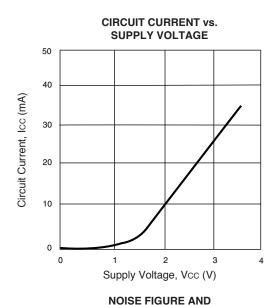
RECOMMENDED OPERATING CONDITIONS

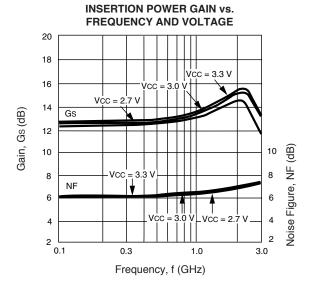
SYMBOLS	PARAMETERS	UNITS	MIN	TYP	MAX
Vcc	Supply Voltage	V	2.7	3	3.3
Тор	Operating Temperature	°C	-40	25	85

TEST CIRCUIT

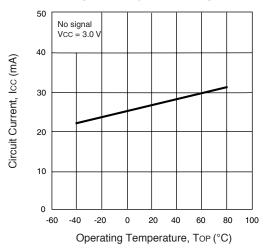


TYPICAL PERFORMANCE CURVES (TA = 25°C)

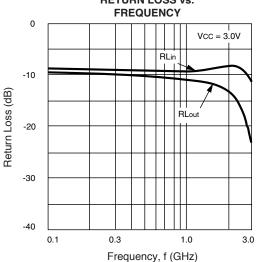




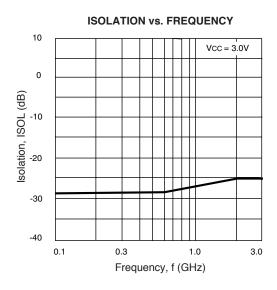
CIRCUIT CURRENT vs. OPERATING TEMPERATURE

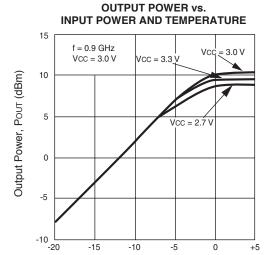


INPUT AND OUTPUT RETURN LOSS vs.

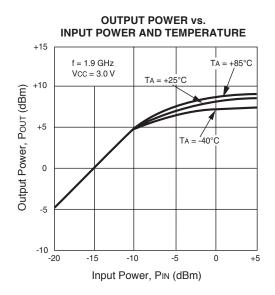


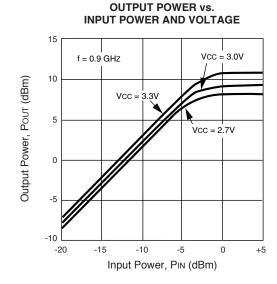
TYPICAL PERFORMANCE CURVES (TA = 25°C)

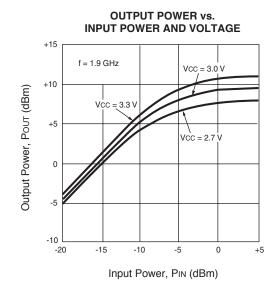


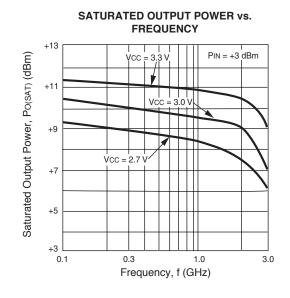


Input Power, PIN (dBm)



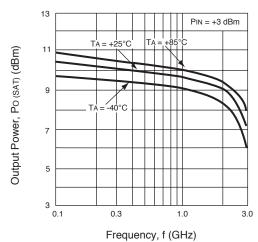




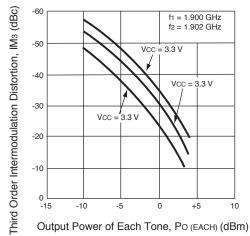


TYPICAL PERFORMANCE CURVES (TA = 25°C)

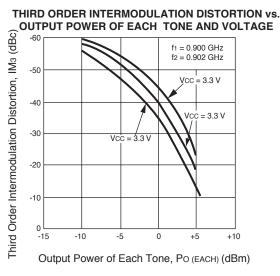
SATURATED OUTPUT POWER vs. FREQUENCY AND TEMPERATURE



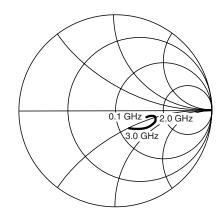
THIRD ORDER INTERMODULATION DISTORTION vs. **OUTPUT POWER OF EACH TONE AND VOLTAGE**

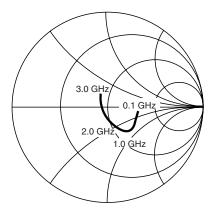


THIRD ORDER INTERMODULATION DISTORTION vs.



TYPICAL SCATTERING PARAMETERS (TA = +25°C, Vcc = Vout = 3.0 V)





Vcc = Vout = 3.0 V, Icc = 29 mA

S11

FREQUENCY	S 11		S 21		S 12		S 22		K
GHz	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG	
0.1	0.338	-1.3	4.560	-3.4	0.039	1.0	0.310	-5.5	2.23
0.2	0.346	-2.0	4.581	-7.6	0.039	2.7	0.311	-9.5	2.20
0.3	0.348	-1.2	4.616	-11.3	0.039	6.8	0.302	-12.3	2.20
0.4	0.340	-1.9	4.661	-15.8	0.040	8.1	0.296	-16.2	2.18
0.5	0.329	-3.1	4.689	-19.5	0.040	11.6	0.290	-20.2	2.20
0.6	0.324	-6.2	4.726	-23.6	0.041	13.7	0.292	-24.1	2.12
0.7	0.341	-8.1	4.844	-27.4	0.042	15.8	0.291	-26.2	2.01
0.8	0.359	-7.6	4.927	-31.5	0.043	18.1	0.292	-28.3	1.90
0.9	0.378	-6.5	5.057	-35.8	0.044	19.3	0.284	-30.9	1.77
1.0	0.375	-5.1	5.179	-41.0	0.045	20.3	0.280	-35.3	1.72
1.1	0.363	-5.2	5.306	-45.9	0.047	22.1	0.285	-40.0	1.64
1.2	0.353	-6.7	5.400	-51.0	0.047	23.7	0.288	-43.4	1.62
1.3	0.357	-8.8	5.567	-56.5	0.048	26.1	0.288	-45.7	1.54
1.4	0.377	-11.7	5.706	-61.7	0.049	24.5	0.285	-47.9	1.44
1.5	0.402	-12.7	5.820	-68.0	0.052	26.7	0.282	-52.8	1.32
1.6	0.414	-13.2	5.987	-73.7	0.052	26.8	0.285	-58.1	1.27
1.7	0.426	-13.6	6.081	-80.1	0.055	29.0	0.288	-62.0	1.18
1.8	0.434	-16.1	6.182	-86.7	0.056	28.2	0.291	-66.1	1.14
1.9	0.448	-19.0	6.229	-93.2	0.057	28.5	0.286	-70.4	1.09
2.0	0.463	-21.7	6.328	-99.7	0.057	28.0	0.282	-76.2	1.07
2.1	0.483	-23.9	6.382	-106.7	0.058	28.5	0.282	-81.5	1.01
2.2	0.492	-25.8	6.431	-113.8	0.058	29.0	0.282	-86.9	0.99
2.3	0.492	-29.7	6.424	-121.2	0.060	30.1	0.278	-91.7	0.99
2.4	0.486	-34.6	6.329	-128.8	0.060	30.2	0.268	-98.4	1.01
2.5	0.489	-40.4	6.146	-136.1	0.062	31.1	0.260	-104.5	1.02
2.6	0.500	-44.6	5.997	-143.1	0.061	32.1	0.251	-111.3	1.05
2.7	0.511	-48.5	5.822	-149.9	0.064	31.4	0.248	-116.7	1.03
2.8	0.511	-50.4	5.693	-157.0	0.066	34.0	0.237	-121.5	1.04
2.9	0.494	-52.9	5.553	-163.0	0.065	33.8	0.222	-128.3	1.11
3.0	0.465	-55.9	5.334	-169.5	0.065	35.5	0.203	-134.5	1.20
3.1	0.441	-60.6	5.157	-175.5	0.066	35.5	0.189	-141.1	1.27

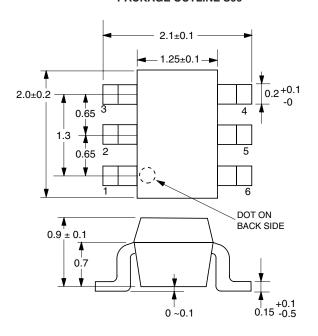
S22

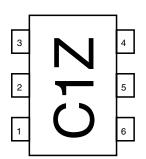
OUTLINE DIMENSIONS (Units in mm)

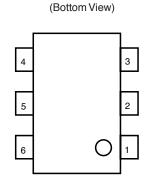
LEAD CONNECTIONS

(Top View)

PACKAGE OUTLINE S06







- 1. INPUT
- 2. GND
- 3. GND
- 4. OUTPUT
- 5. GND
- 6. Vcc

PIN DESCRIPTIONS

Pin No.	Pin Name	Applied Voltage (V)	Description	Internal Equivalent Circuit
1	Input	_	Signal input pin. An internal matching circuit, configured with resistors, enables 50 Ω connection over a wide bandwidth. A multi-feedback circuit is designed to cancel the deviations of hFE and resistance. This pin must be coupled to the signal source with a blocking capacitor.	®
4	Output		Signal output pin. Connect an inductor between this pin and Vcc to supply current to the internal output transistors.	
6	Vcc	2.7 to 3.3	Power supply pin. This pin should be externally equipped with a bypass capacitor to minimize ground impedance.	
2 3 5	GND	0	Ground pins. These pins should be connected to system ground with minimum inductance. Ground pattern on the board should be formed as wide as possible. All the ground pins must be connected together with wide ground pattern to minimize impedance difference.	1

ORDERING INFORMATION

PART NUMBER	QTY
UPC2762TB-E3-A	3K/Reel

Note:

Embossed Tape, 8 mm wide. Pins 1, 2 and 3 face perforated side of tape

Life Support Applications

These NEC products are not intended for use in life support devices, appliances, or systems where the malfunction of these products can reasonably be expected to result in personal injury. The customers of CEL using or selling these products for use in such applications do so at their own risk and agree to fully indemnify CEL for all damages resulting from such improper use or sale.

EXCLUSIVE NORTH AMERICAN AGENT FOR **NEC** RF, MICROWAVE & OPTOELECTRONIC SEMICONDUCTORS

CALIFORNIA EASTERN LABORATORIES • Headquarters • 4590 Patrick Henry Drive • Santa Clara, CA 95054-1817 • (408) 988-3500 • Telex 34-6393 • FAX (408) 988-0279 24-Hour Fax-On-Demand: 800-390-3232 (U.S. and Canada only) • Internet: http://WWW.CEL.COM

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06/12/2000



4590 Patrick Henry Drive Santa Clara, CA 95054-1817 Telephone: (408) 919-2500

Facsimile: (408) 988-0279

Subject: Compliance with EU Directives

CEL certifies, to its knowledge, that semiconductor and laser products detailed below are compliant with the requirements of European Union (EU) Directive 2002/95/EC Restriction on Use of Hazardous Substances in electrical and electronic equipment (RoHS) and the requirements of EU Directive 2003/11/EC Restriction on Penta and Octa BDE.

CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The –AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)	Concentration contained in CEL devices		
Lead (Pb)	< 1000 PPM	-A Not Detected	-AZ (*)	
Mercury	< 1000 PPM Not E		etected	
Cadmium	< 100 PPM	Not Detected		
Hexavalent Chromium	< 1000 PPM	Not De	etected	
PBB	< 1000 PPM	< 1000 PPM Not Detected		
PBDE	< 1000 PPM	Not Detected		

If you should have any additional questions regarding our devices and compliance to environmental standards, please do not hesitate to contact your local representative.

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